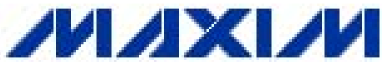

RELIABILITY REPORT

FOR

MAX8667ETEAB+

PLASTIC ENCAPSULATED DEVICES

September 2, 2011

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
Sokhom Chum
Quality Assurance
Reliability Engineer

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Conclusion

The MAX8667ETEAB+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX8667/MAX8668 dual step-down converters with dual low-dropout (LDO) linear regulators are intended to power low-voltage microprocessors or DSPs in portable devices. They feature high efficiency with small external component size. The step-down converters are adjustable from 0.6V to 3.3V (MAX8668) or factory preset (MAX8667) with guaranteed output current of 600mA for OUT1 and 1200mA for OUT2. The 1.5MHz hysteretic-PWM control scheme allows for tiny external components and reduces no-load operating current to 100µA with all outputs enabled. Dual low-quiescent-current, low-noise LDOs operate down to 1.7V supply voltage. The MAX8667/MAX8668 have individual enables for each output, maximizing flexibility. The MAX8667/MAX8668 are available in the space-saving, 3mm x 3mm, 16-pin thin QFN package.

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II. Manufacturing Information

A. Description/Function:	1.5MHz Dual Step-Down DC-DC Converters with Dual LDOs and Individual Enables
B. Process:	S4
C. Number of Device Transistors:	
D. Fabrication Location:	Texas
E. Assembly Location:	China
F. Date of Initial Production:	April 16, 2007

III. Packaging Information

A. Package Type:	16L TQFN 3x3
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (2 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-2320 / A
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	64°C/W
K. Single Layer Theta Jc:	7°C/W
L. Multi Layer Theta Ja:	48°C/W
M. Multi Layer Theta Jc:	7°C/W

IV. Die Information

A. Dimensions:	61 X 61 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

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V. Quality Assurance Information

A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 48 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 22.9 \times 10^{-9}$

λ = 22.9 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the S45 Process results in a FIT Rate of 0.49 @ 25C and 8.49 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot SW00BQ001D D/C 0701)

The PP69 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA.

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Table 1
Reliability Evaluation Test Results

MAX8667ETEAB+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0	SW00BQ001D, D/C 0701

Note 1: Life Test Data may represent plastic DIP qualification lots.

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